

Exhibition fees

Category	1 booth/7.5m ² *tax excluded
Non-Members	Yen 375,000
Members ^{*1}	Yen 320,000

^{*1} Members of the WECC member associations (CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA and TPCA).
* Booth area is change from 9m² to 75m².
* Booth construction, cleaning, electricity, Water Supply, etc. is not included in the exhibition fee.

How to apply

Please fill out the Application Form in consideration with ofllows:
– Carefully read the “Exhibition Regulations”
– Select the exhibition based on your product
The Secretariat Office will send the invoice or exhibitor who apply on the online will be able to download from exhibitor portal. Based on the invoice, please make the payment by the due date.

Deadline

January 31, 2020

If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
until February 1	50% of booth fees
From February 2 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

January	February	April	May
▲ January 31 Application deadline	▲ February 18 Exhibitors’ Briefing (Tokyo) February 20 Exhibitors’ Briefing (Osaka)	Sending invitations Mid-April Deadline for submission of application documents Starting registration to the exhibition Last-April	May 25 to 26 Installation period May 27 to 29 Exhibition open * Immediate removal on the last day

【venue: Aomi Exhibition Hall】

Use of the venue is restricted due to the Olympic and Paralympic Games Tokyo 2020. The exhibition area is 80% shrink from the previous show. We might not accept increasing the number of booths or request to decrease the number of booths. Thank you for your corporation.

Booth size

:

Booth area is change from 9m² to 75m².

Floor Layout

:

Details of floor layout will be informed on the website.

Determination of Booth Location

:

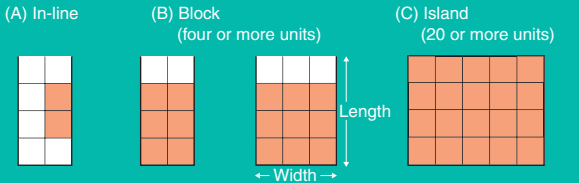
Booth locations will be determined by the organizers based on factors such as the number of exhibition booths, past participation, and membership, and will be announced at the Exhibitors’ Briefing.

Booth Fixtures and Decorations

:

To set up and remove your booth efficiently, please cooperate in your using a package booth. Details will be informed at a later date.

Booth type

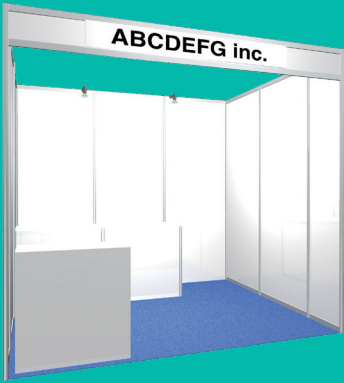


Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth

Price: ¥ 73,000 (excluding tax)
Materials: System panel
Specifications and prices are subject to change.



50th International Electronic Circuits Exhibition

34th ADVANCED ELECTRONICS PACKAGING EXHIBITION

22nd Jisson Process Technology Exhibition

IoT supporting semiconductor /circuit board exhibition

Electrical /optical transmission technology Exhibition

Smart Sensing

Japan Federation Of Electronic Parts Distributors And Dealers
Tokyo Electronics Appliances Wholesalers Association

E-Textile



のせる つなぐ つくる そして ひろげる

5.27 ▶ 5.29 The Exhibition Guide

Tokyo Big Sight Aomi Exhibition Hall + TFT Hall

Comprehensive exhibition of technology embodying 5G, automobile, IoT, robots, wearable, etc.

The Total Solution Exhibition 2020

www.jpccashow.com

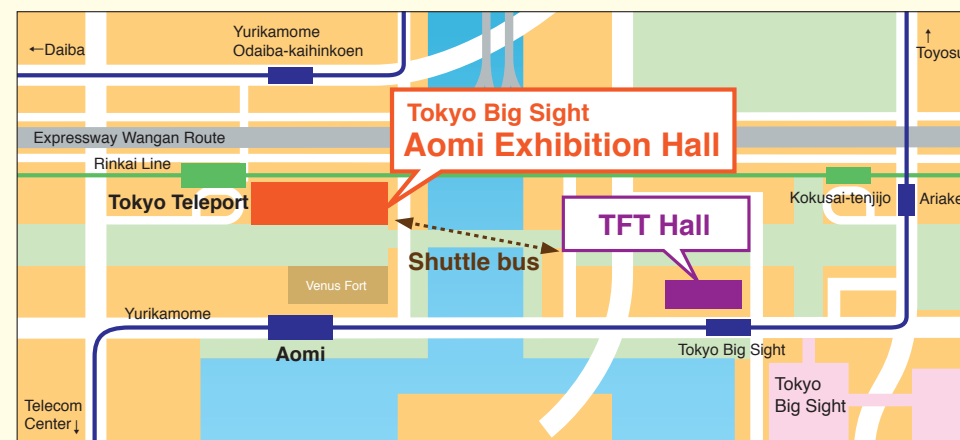
Comprehensive exhibition of technology embodying 5G, automobile, IoT, robots, wearable, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world



The Total Solution
Exhibition 2020
www.jpccashow.com

Aomi Exhibition Hall / TFT Hall Access



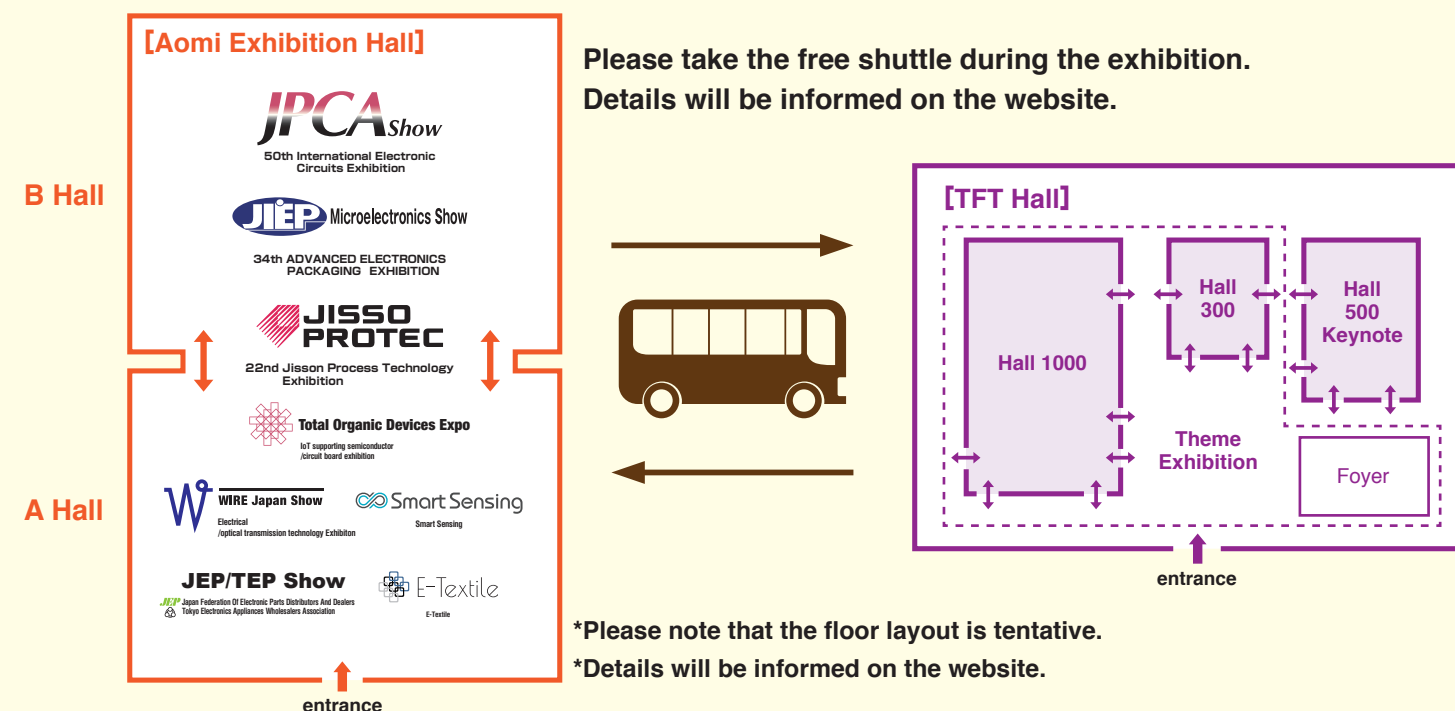
The nearest station to Aomi Exhibition Hall

- Approx. 4-minutes walk from Aomi Station, Yurikamome
- Approx. 2-minutes walk from Tokyo-teleport Station, Rinkai Line

The nearest station to TFT Hall

- Approx. 1-minutes walk from Tokyo Big Sight Station, Yurikamome
- Approx. 5-minutes walk from Kokusai-tenjijo Station, Rinkai Line

Floor Layout (Tentative)



Result of 2019

会場 Tokyo Big Sight West Hall 1-4
+Conference Tower

Exhibit scale 507 companies
1,372 spaces

Number of visitors 44,110 people

Number of seminar audiences 11,421 people

Free

Presentation by exhibitors

The presentation will provide an opportunity to increase your presence at the exhibition. Publicize information that cannot be communicated by panels, posters and other tools!!

- Seminar hall (Thirty-minute presentation)
- Equipment for presentation is fully provided.

* Lecture time and date can be selected on a first-come-first-served basis.

Main companies visiting the exhibition

- Related to automobile: Aisin Seiki, Asahi Denso, ICHIKOH INDUSTRIES, Calsonic Kansei, Keihin, KOA, KOITO MANUFACTURING, STANLEY ELECTRIC, Sumitomo Wiring Systems, DAIHATSU MOTOR, DENSO, TOKAI RIKI, Toyodenso, TOYOTA MOTOR, NISSAN MOTOR, NHK SPRING, PIONEER, Hitachi Automotive Systems, Hino Motors, SUBARU, Honda Motor, Mazda Motor, MITSUBISHI MOTORS, YAZAKI
- OA/Robotics: OMRON, KEYENCE, Canon, KONICA MINOLTA, CYBERDYNE, SANYO DENKI, JUKI, SEIKO EPSON, Panasonic, Panasonic Smart Factory Solutions, FANUC, FUJI, Fuji Xerox, Mitsubishi Electric, YASKAWA Electric, Yamaha Motor, Ricoh Industry, RICOH JAPAN
- Related to information and communication: Apple, Intel, NHK Media Technology, NTT, NTT DOCOMO, Oki Electric Industry, Korean Broadcasting System (KBS), KYOCERA, KDDI, SoftBank, TOKYO BROADCASTING SYSTEM HOLDINGS (TBS), Toshiba Information Systems (Japan), IBM Japan, NEC, Microsoft Japan, Nihon Unisys, Panasonic, PFU, Hitachi, Huawei, Fujikura, FUJITSU, Murata Manufacturing
- Related to AV and home electrical appliances: LG Electronics, CASIO COMPUTER, Canon, Samsung Electronics, Sharp, Sony, Sony Global Manufacturing & Operations, Sony Semiconductor Solutions, DAIKIN INDUSTRIES, NIKON, PIONEER, Panasonic, FUJITSU GENERAL, YAMAHA, Roland
- Related to medical equipment: Olympus, Siemens, SHIMADZU, SHIRAKAWA OLYMPUS, Terumo, Canon Medical Systems, Hitachi High-Technologies, Hitachi Healthcare Manufacturing, Fujifilm, MARK ELECTRONICS, MORITA TOKYO MFG
- Related to semiconductor device: Intel, STMicroelectronics, Canon, Samsung Electronics, SCREEN Holdings, Sony, TDK, Tokyo Electron, Toshiba Memory, NIKON, Hitachi High-Technologies, FUJITSU SEMICONDUCTOR, Micron Japan, Renesas Electronics, ROHM
- Related to aerospace: IHI, NEC Space Technologies, JAXA (Japan Aerospace Exploration Agency), SINFONIA TECHNOLOGY, Nabtesco, Nippon Avionics, NEC, Mitsubishi Heavy Industries, Mitsubishi Electric
- Other: Japan Maritime Self-Defense Force, Japan Ground Self-Defense Force, Tokyo Gas, Tokyo Electric Power, Central Japan Railway, WEST JAPAN RAILWAY, East Japan Railway, Mizuho Bank
- Electronic circuit board: ADVANTEST, Eastern, IBIDEN, ELNA, Kyoei Sangyo, KYOSHA, KYOCERA, Kyoden, Shirai Electronics Industrial, SHINKO, SHINKO ELECTRIC INDUSTRIES, Sumitomo Electric Printed Circuits, DAISHO DENSHI, Nitto Denko, CMK, NIPPON MEKTRON, Panasonic, Hitachi Chemical, Fujikura, FUJITSU INTERCONNECT TECHNOLOGIES, Meiko Electronics, Yamashita Materials, RISHO KOGYO

Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology



- PWB Tech
Finished Products, Design Technologies, Reliability and Inspection Technologies, Main Materials, Processing Technologies, Materials and Equipment, Manufacturing Equipment, Environmental Systems, Distribution Systems
- Module JAPAN
Module board/Module Board mounting / General technology for built-in parts (Finished Products / Related Products / Design / Reliability inspection / Materials / Functional materials / Related equipment / Related system)
- Flexible Printed Circuits Products Area
General technology for Flexible Printed Circuits (Manufacturing)
- EMS Japan
General contracted services related to EMS, Electronic electrical equipments, and Semiconductors
[Organizer: Japan Electronics Packaging and Circuits Association]

High-density packaging technologies



General technology for implementation and electric technology (Materials/Circuit and Mounting design / High speed high frequency/Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)
[Organizer: Japan Institute of Electronics Packaging]

Electronic Component Packaging Technologies



General technology for Electronic Component Packaging Technologies (Electronic component mounting machine / Semiconductor mounting equipment - System / nspection technology / Mounting design system / Robots)
[Organizer: Japan Robot Association]

New circuit fabrication technology



General technology for Organic Devices (Products and parts of Printed Electronics / MEMS / Sensor LED / OLED / Applied products for Organic semiconductor)
[Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)]

Electrical/optical transmission technology



General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)
[Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD.)]

Sensor technology



General technology for Sensor and Sensing System (Sensors, Sensor Nodes, Semiconductors, Parts and Devices, Electronics, Telecommunications Devices, Network Systems, Software, Data Platform, Power Sources, Other Related Devices, Technologies and Services)
[Co-organizers: Japan Electronics Packaging and Circuits Association, Communication Design, Inc.]

Semiconductors and Electronic parts



General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)
[Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association]

Highly functional textile



A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)
[Co-organizers: Japan Electronics Packaging and Circuits Association, e-Textile research group of Fukui]